



DO214AB (SMC) Rectifier

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu),	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 31.19%	Copper (Cu)	7440-50-8	51.7800	99.9787	204,930.5
	Phosphorus (P)	7723-14-0	0.0005	0.0010	2.0
	Arsenic (As)	7440-38-2	0.0005	0.0010	2.0
	Tin (Sn)	7440-31-5	0.0005	0.0010	2.0
	Oxygen (O)	7782-44-7	0.0003	0.0005	1.0
	Sulfur (S)	7704-34-9	0.0062	0.0120	24.6
	Iron (Fe)	7439-89-6	0.0003	0.0007	1.4
	Nickel (Ni)	7440-02-0	0.0002	0.0003	0.6
	Bismuth (Bi)	7440-69-9	0.0010	0.0020	4.1
	Antimony (Sb)	1309-64-4	0.0010	0.0020	4.1
	Lead (Pb)	7439-92-1	0.0003	0.0005	1.0
	Zinc (Zn)	7440-66-6	0.0002	0.0003	0.6
	Total		51.79		
Solder Wafer 0.98%	Lead (Pb)	7439-92-1	1.59	92.50	6,296.7
	Tin (Sn)	7440-31-5	0.09	5.00	340.4
	Silver (Ag)	7440-22-4	0.04	2.50	170.2
	Total		1.72		
Chip 1.30%	Silicon (Si)	7440-21-3	1.565	95.40	6,192.1
	Lead (Pb)	7439-92-1	0.075	4.60	298.6
	Total		1.64		
Molding 65.86%	Silica (SiO ₂)	7631-86-9	145.7003	74.11	576,640.2
	Epoxy resin	29690-82-2	33.4220	17.00	132,274.8
	Phenolic resin	9003-35-4	17.3008	8.80	68,471.6
	Phosphorus(P)	7723-14-0	0.0983	0.05	389.0
	Carbon Black	1333-86-4	0.0786	0.04	311.2
	Total		196.60		
Plating 0.67%	Tin (Sn)	7440-31-5	0.92	100.00	3,641.1
	Total		0.92		
	Total mass (mg)		252.67		